

## PRESS RELEASE

**Contact for EBARA Technologies, Inc.:**

*Bill Stowell, Product Market Dept.*

*Phone: 845. 231. 3505*

*E-mail: [bstowell@ebaratech.com](mailto:bstowell@ebaratech.com)*

*[www.ebaratech.com](http://www.ebaratech.com)*

### **EBARA Technologies Inc. Advances Copper Plating Capabilities With Launch Of The E-REX ECP Electrochemical Plating System**

**SACRAMENTO, Calif., July 12, 2005** - EBARA Technologies, Inc. today introduced the new E-REX 300 ECP Electrochemical Plating System. This new system addresses process challenges associated with 45 nm and 32 nm node plating technology. Additionally the E-REX is extendable to direct on barrier applications with no hardware modifications providing chip manufacturers with increased flexibility.

The E-REX eliminates seed film dependant plating performance through the use of EBARA's patented PRE (Porous Resistive Element), along with an edge profile control mechanism, providing uniform film deposition rates across the entire wafer regardless of variations in seed film thickness and plating chemistry.

The E-REX provides high-speed solution introduction, face-up wafer orientation and an inert anode. The inert anode is maintenance free and contributes to the E-REX's low CoC while the high-speed solution introduction reduces the defects associated typical wafer face down immersion technologies.

Find out more about EBARA's E-REX and visit EBARA at Semicon, booth #1540 in the South Hall.

**Forward-Looking Statements:** This press release, except for historical information, contains forward looking statements, including statements relating to the approval, use and benefits of the E-REX, and is subject to the safe harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such statements are based on current expectations and are subject to uncertainties and changes in condition, significance, value and effect as well as other risks, which could cause actual results to vary from expectations. All forward-looking statements are based on the company's approximations, predictions and beliefs. The Company undertakes no obligation to update the information or statements made in this press release.

EBARA Technologies, Inc. is a U.S. based subsidiary of EBARA Corporation, a Japanese company founded in 1912, which provides a wide range of technologies including equipment, systems and services for water, air and the environment. EBARA Technologies, Inc. is a leading global innovator and worldwide supplier of vacuum technologies and advanced wafer-processing equipment for clean environments within the semiconductor industry. Specifically, EBARA Technologies manufactures a full line of Dry Mechanical Pumps and associated monitoring systems for the semiconductor industry's toughest applications, including low-pressure chemical vapor deposition (LPCVD), etch, EPI and CVD. The company's offerings also include Turbo Molecular Pumps, Point-of-Use Abatement Systems, Clean Box (wafer carrier and storage unit), EPIX Filters (airborne molecular chemical filters), Ozone Related Equipment, Chemical Mechanical Polishers (CMP), Electrochemical Plating Systems (ECP), and Through-Mask Plating Systems (ThMP). EBARA maintains a superior worldwide sales and support network with over 30 worldwide locations. Additional information about EBARA Technologies, Inc. and its products can be found on the World Wide Web at [www.ebaratech.com](http://www.ebaratech.com).